

Claims

1 1. A flex interconnection circuit substrate, comprising:
2 a connector bonding site coupled to an electronic component collection bonding
3 site; and
4 said electronic component collection bonding site coupled to at least one MR
5 read-write head bonding site;
6 wherein said electronic component collection includes at least one preamplifier.

1 2. The apparatus of Claim 11,
2 wherein said electronic components collection further includes at least one
3 member of the collection comprising a resistor and a capacitor.

1 3. A flex interconnection circuit, comprising:
2 said flex interconnection circuit substrate of Claim 11;
3 a connector bonded to said connector bonding site;
4 said electronics component collection bonded to said electronics component
5 collection bonding site comprising at least said preamplifier bonded to said electronic
6 component bonding site; and
7 at least one MR read-write head bonded to said MR read-write head bonding site;
8 wherein said flex interconnection circuit couples said connector and said
9 preamplifier;
10 wherein said flex interconnection circuit couples said preamplifier and said MR
11 read-write head.

1 4. Said flex interconnection circuit of Claim 13, further comprising:
2 a second MR read-write head bonded to said MR read-write head bonding site;
3 wherein said flex interconnection circuit couples said preamplifier and said
4 second MR read-write head.

1 5. An actuator, comprising:

2 a head slider affixed with said MR read-write head of said flex interconnection
3 circuit of Claim 13;
4 said flex interconnection circuit anchored about said preamplifier to said actuator;
5 and
6 at least one binding of said flex interconnection circuit between said preamplifier
7 and said MR read-write head.

1 6. A disk drive, comprising:
2 said actuator of Claim 15 coupled by said connector to a disk drive controller
3 printed circuit board.